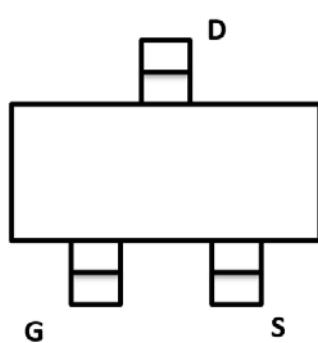
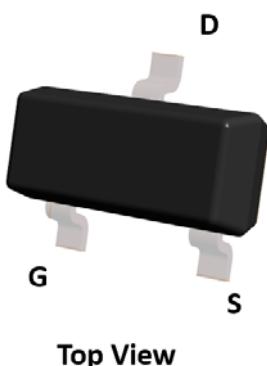
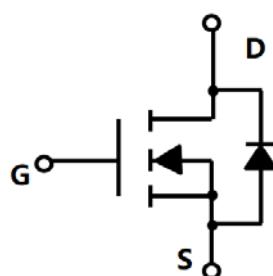


## N-Channel Enhancement Mode Field Effect Transistor

**SOT-23**

### Product Summary

• $V_{DS}$	20V
• $I_D$	4.3A
• $R_{DS(ON)}$ (at $V_{GS} = 4.5V$ )	< 27mohm
• $R_{DS(ON)}$ (at $V_{GS} = 2.5V$ )	< 37mohm

### General Description

- Trench Power LV MOSFET technology
- High Density Cell Design for Low  $R_{DS(ON)}$
- High Speed switching
- Part no. with suffix "Q" means AEC-Q101 qualified

### Applications

- Battery protection
- Load switch
- Power management

### ■ Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	20	V
Gate-source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current  $T_A=25^\circ C$	$I_D$	4.3	A
$T_A=70^\circ C$	$I_D$	3.4	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	17.2	A
Total Power Dissipation @ $T_A=25^\circ C$ Steady State	$P_D$	1	W
Thermal Resistance Junction-to-Ambient <sup>B</sup>	$R_{\theta JA}$	125	$^\circ C / W$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ C$

### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL2302AQ	F2	.2302.	3000	30000	120000	7" reel



# YJL2302AQ

**■ Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}= 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}= 20\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 10\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}= 250\mu\text{A}$	0.55	0.85	1.25	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}= 4.3\text{A}$		21	27	$\text{m}\Omega$
		$V_{\text{GS}}= 2.5\text{V}, I_{\text{D}}= 3.0\text{A}$		28	37	
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}= 4.3\text{A}, V_{\text{GS}}=0\text{V}$		0.8	1.2	V
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHZ}$		602		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			79		
Reverse Transfer Capacitance	$C_{\text{rss}}$			62		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{\text{GS}}= 4.5\text{V}, V_{\text{DS}}= 10\text{V}, I_{\text{D}}= 4.3\text{A}$		6.5		$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$			1.6		
Gate-Drain Charge	$Q_{\text{gd}}$			1.5		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F= 15\text{A}, dI/dt=100\text{A/us}$		0.6		$\text{ns}$
Reverse Recovery Time	$t_{\text{rr}}$			9.9		
Turn-on Delay Time	$t_{\text{D(on)}}$			8		
Turn-on Rise Time	$t_r$	$V_{\text{GS}}= 4.5\text{V}, V_{\text{DS}}= 10\text{V}, I_{\text{D}}= 6.7\text{A}$ $R_{\text{GEN}}= 3\Omega$		58		$\text{ns}$
Turn-off Delay Time	$t_{\text{D(off)}}$			20		
Turn-off fall Time	$t_f$			68		

A. Pulse Test: Pulse Width  $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$ .

B.  $R_{\theta JA}$  is the sum of the junction-to-lead and lead-to-ambient thermal resistance, where the lead thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JL}$  is guaranteed by design, while  $R_{\theta JA}$  is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.

### ■ Typical Performance Characteristics

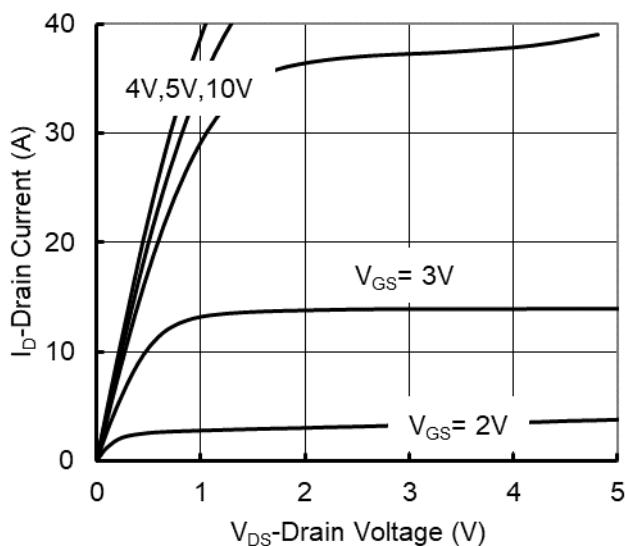


Figure 1. Output Characteristics

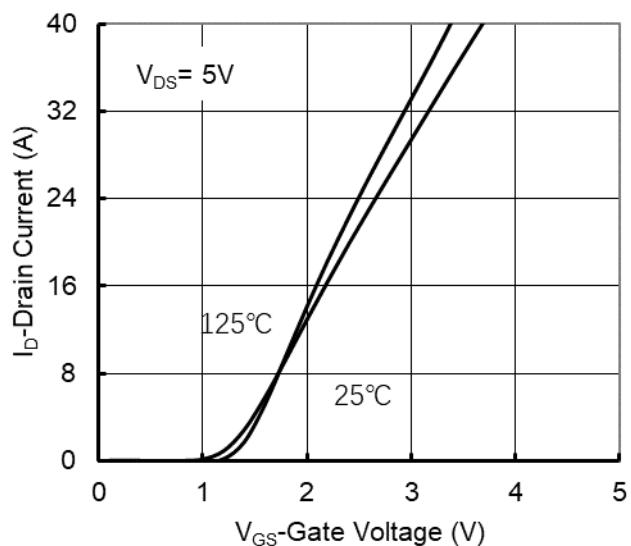


Figure 2. Transfer Characteristics

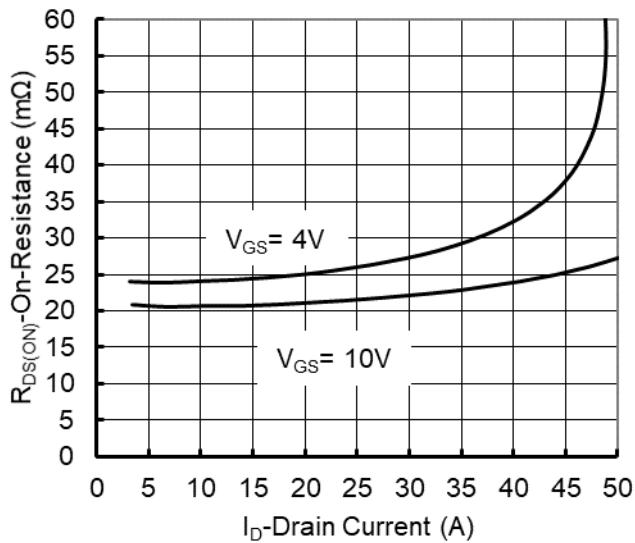


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

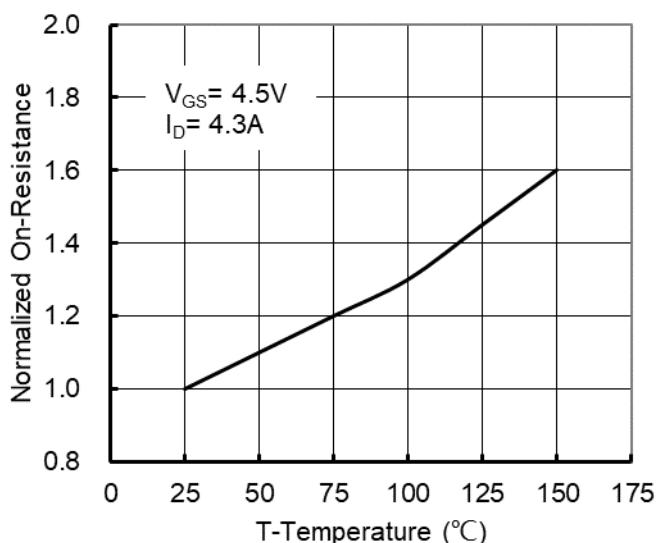


Figure 4: On-Resistance vs. Junction Temperature

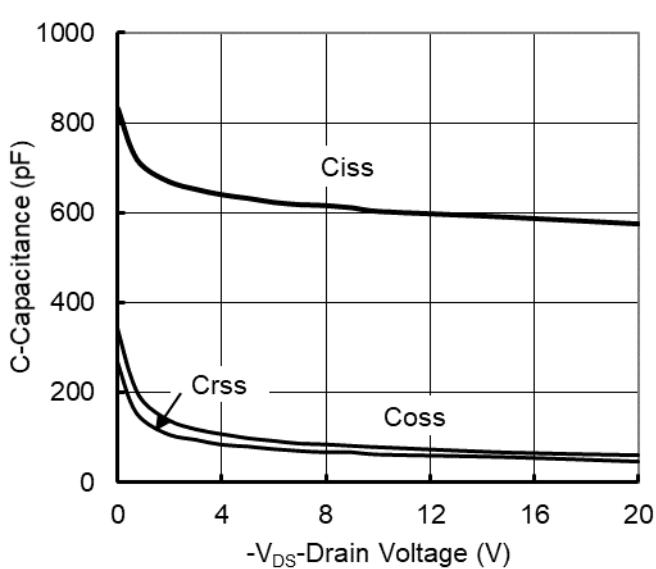


Figure 5. Capacitance Characteristics

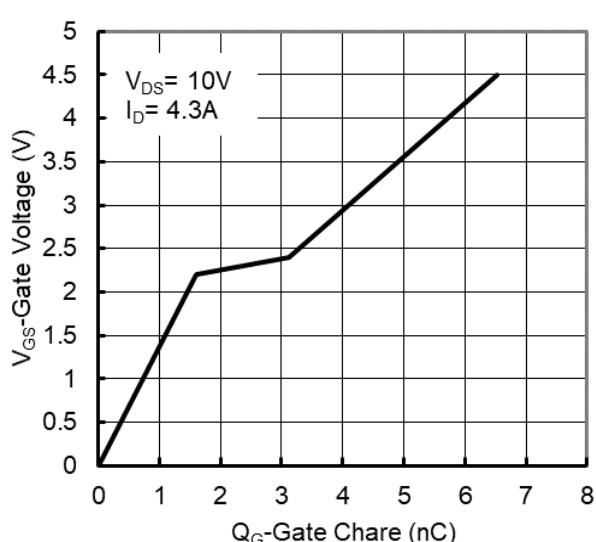
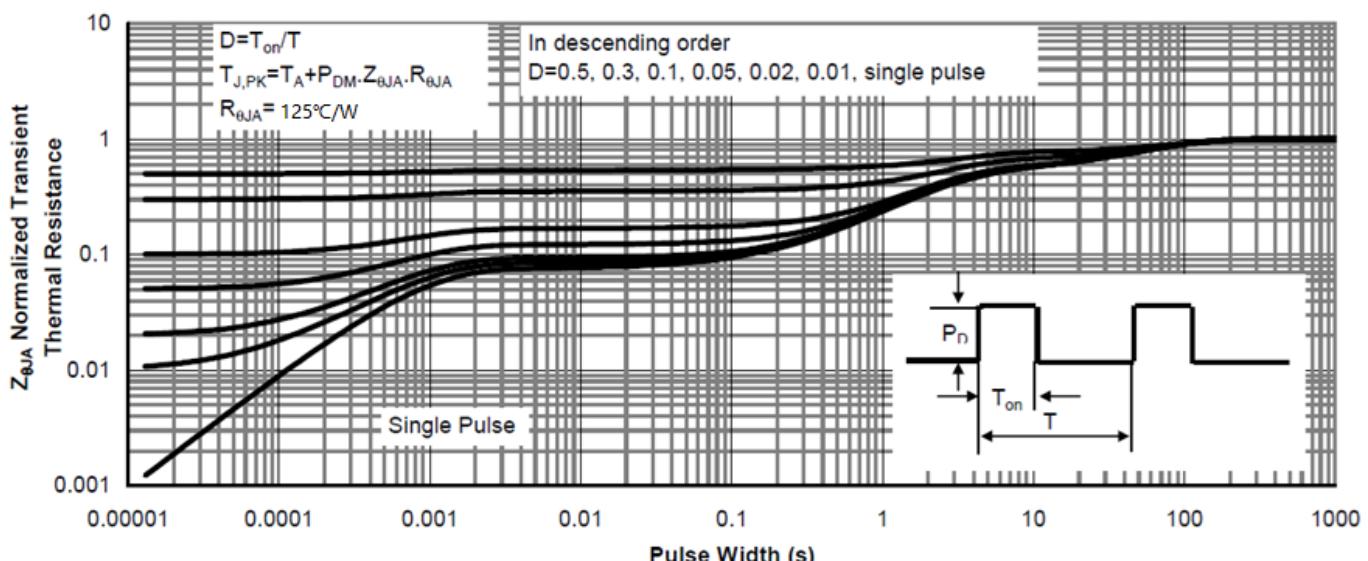
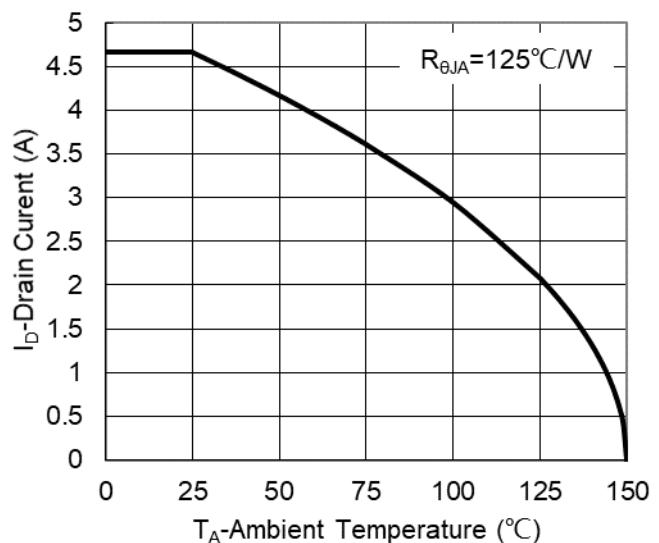
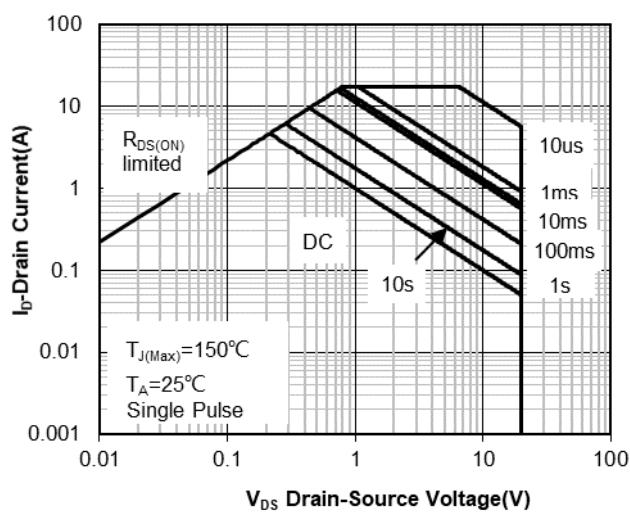
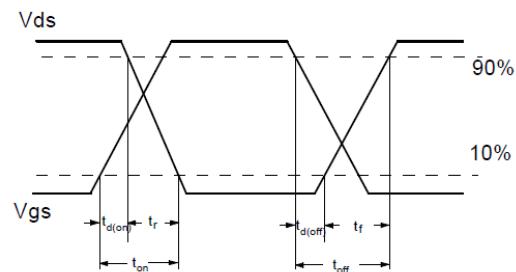
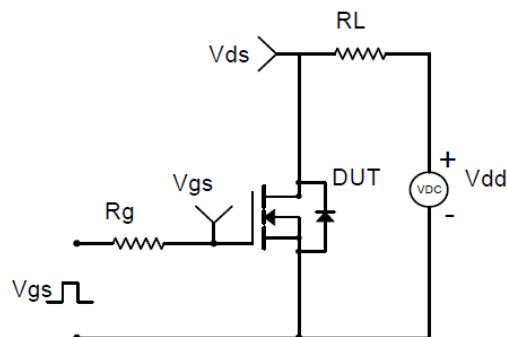
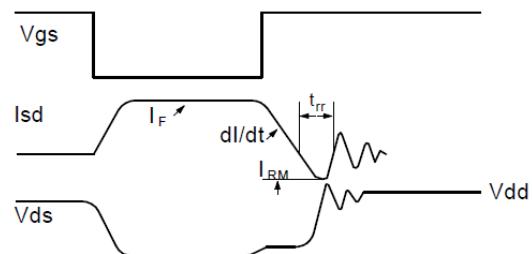
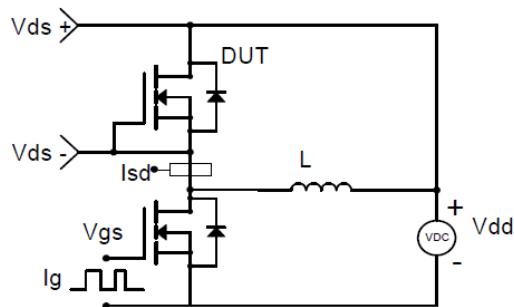
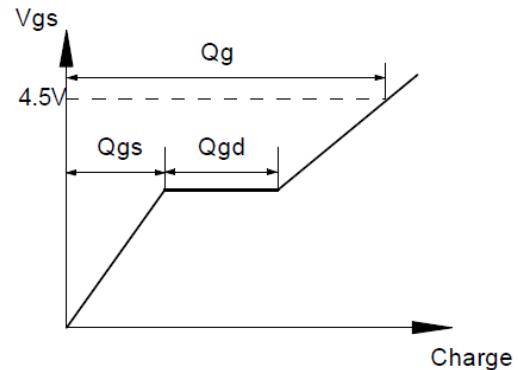
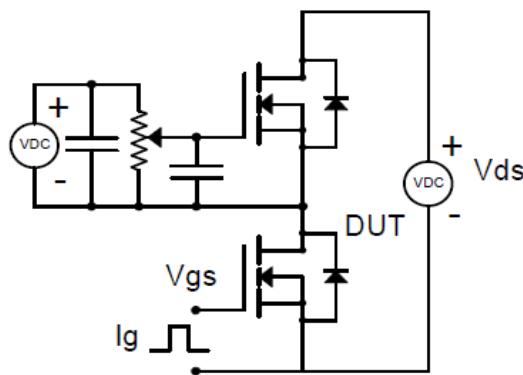
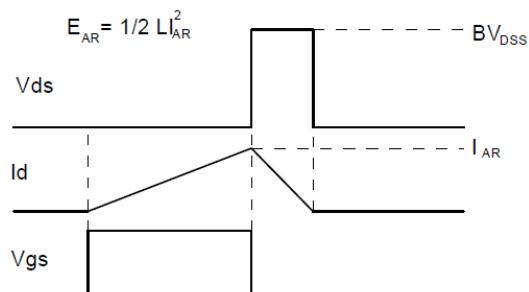
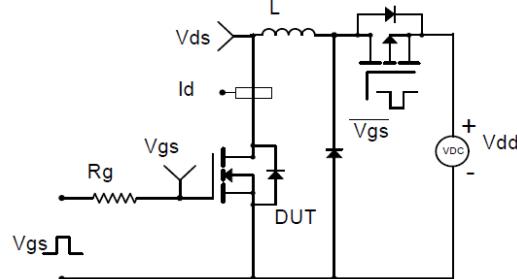
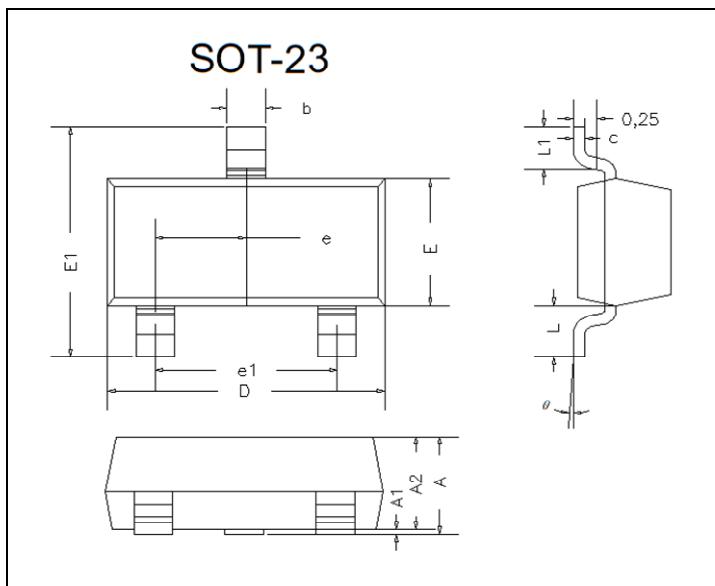


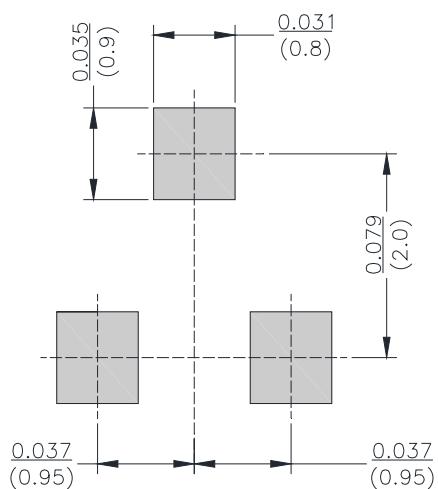
Figure 6. Gate Charge




**Resistive Switching Test Circuit & Waveforms**

**Diode Recovery Test Circuit & Waveforms**

**Gate Charge Test Circuit & Waveform**

**Unclamped Inductive Switching (UIS) Test Circuit & Waveforms**

**■ SOT-23 Package information**

DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.035	0.045	0.90	1.15	
A1	0.000	0.004	0.00	0.10	
A2	0.035	0.041	0.90	1.05	
b	0.012	0.020	0.30	0.50	
c	0.004	0.008	0.10	0.20	
D	0.110	0.118	2.80	3.00	
E	0.047	0.055	1.20	1.40	
E1	0.089	0.100	2.25	2.55	
e	0.370TYP		0.95TYP		
e1	0.071	0.079	1.80	2.00	
L	0.220REF		0.55REF		
L1	0.012	0.020	0.30	0.50	
θ	0°	8°	0°	8°	

**■ SOT-23 Suggested Pad Layout**



## Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with automotive electronics, are not designed for use in medical, life-saving, lifesustaining, or military. Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.21yangjie.com>, or consult your nearest Yangjie's sales office for further assistance.